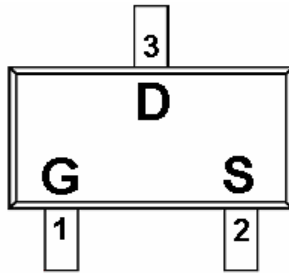


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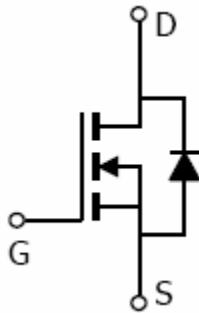
Dual N Channel Enhancement Mode MOSFET  
**0.65A**

**DESCRIPTION**

DMG1012T is the N-Channel enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance and provide superior switching performance. These devices are particularly suited for low voltage applications such as notebook computer power management and other battery powered circuits where high-side switching, low in-line power loss, and resistance to transients are needed.

**PIN CONFIGURATION**  
**SOT-523 / SC-89****FEATURE**

- 20V/0.65A,  $R_{DS(ON)} = 380\text{ohm}@V_{GS} = 4.5\text{V}$
- 20V/0.55A,  $R_{DS(ON)} = 450\text{ohm}@V_{GS} = 2.5\text{V}$
- 20V/0.45A,  $R_{DS(ON)} = 800\text{ohm}@V_{GS} = 1.8\text{V}$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional low on-resistance and maximum DC current capability
- SOT-523 / SC89 package design



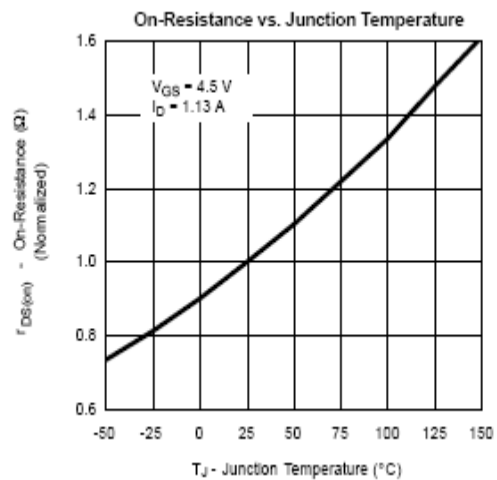
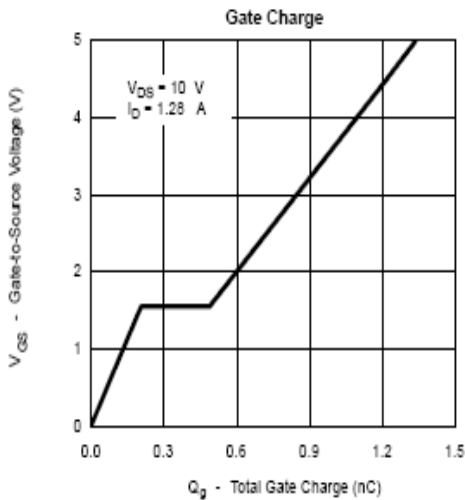
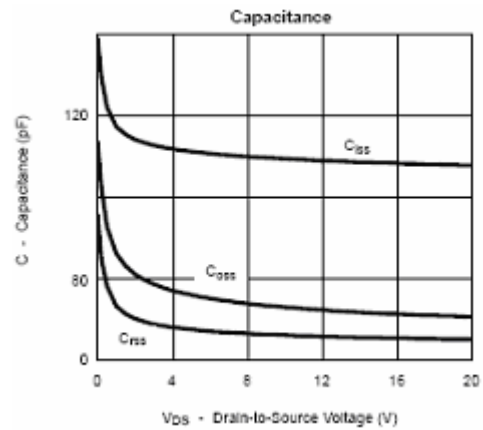
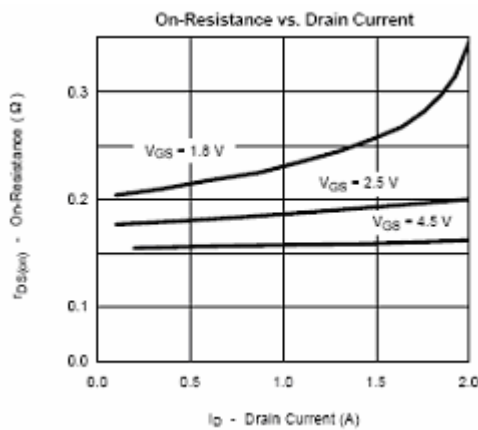
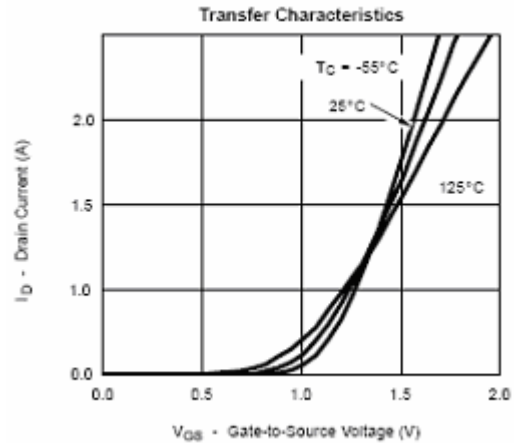
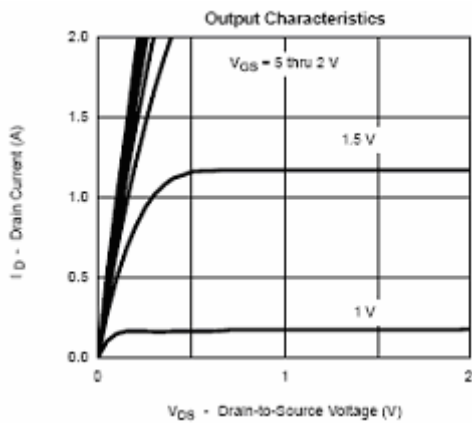
**ABSOLUTE MAXIMUM RATINGS** ( $T_a = 25^\circ\text{C}$  Unless otherwise noted )

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	+/-12	V
Continuous Drain Current ( $T_J=150^\circ\text{C}$ )	$I_D$	$T_A=25^\circ\text{C}$ 0.65	A
		$T_A=80^\circ\text{C}$ 0.45	
Pulsed Drain Current	$I_{DM}$	1.0	A
Continuous Source Current (Diode Conduction)	$I_S$	0.3	A
Power Dissipation	$P_D$	$T_A=25^\circ\text{C}$ 0.27	W
		$T_A=70^\circ\text{C}$ 0.16	
Operation Junction Temperature	$T_J$	-55/150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55/150	$^\circ\text{C}$

Dual N Channel Enhancement Mode MOSFET  
**0.65A**
**ELECTRICAL CHARACTERISTICS** ( Ta = 25°C Unless otherwise noted )

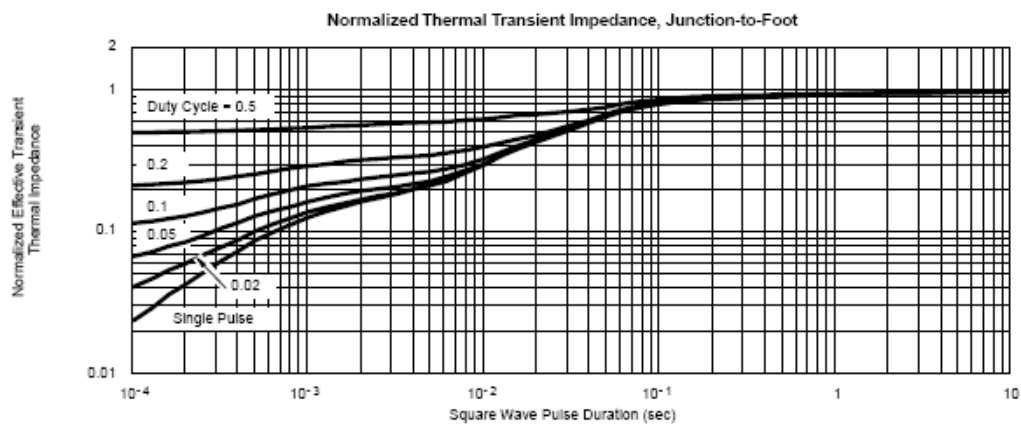
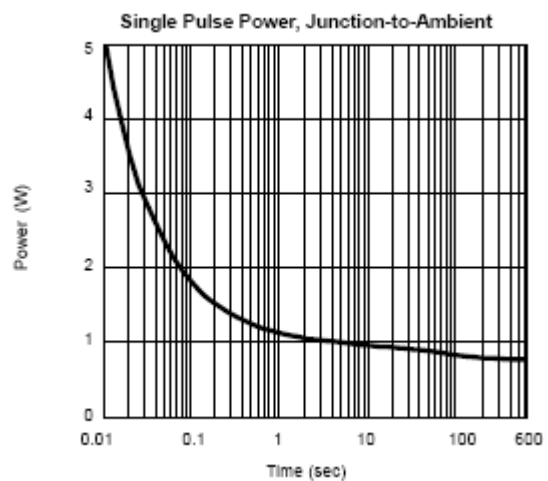
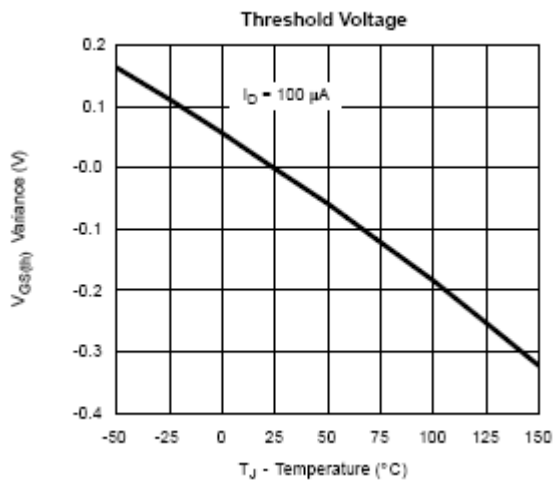
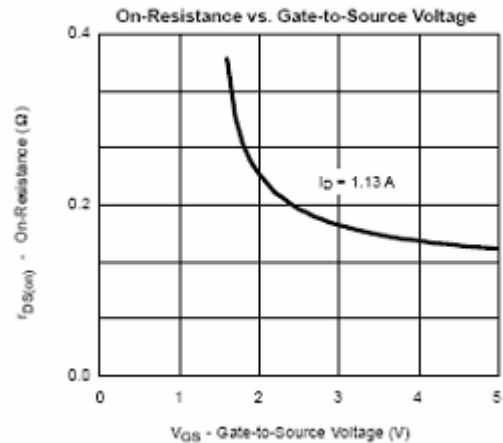
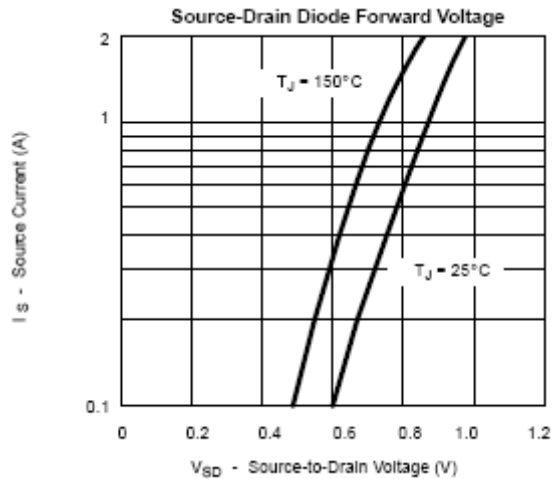
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	20			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.35		1.0	V
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=+/-12V$			100	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=20V, V_{GS}=0V$			1	uA
		$V_{DS}=20V, V_{GS}=0V$ $T_J=55^\circ C$			5	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \leq 4.5V, V_{GS}=5V$	0.7			A
Drain-source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=0.65A$		260	380	mΩ
		$V_{GS}=2.5V, I_D=0.55A$		320	450	
		$V_{GS}=1.8V, I_D=0.55A$		420	800	
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=0.4A$		1.0		S
Diode Forward Voltage	$V_{SD}$	$I_S=0.15A, V_{GS}=0V$		0.8	1.2	V
<b>DYNAMIC</b>						
Total Gate Charge	$Q_g$	$V_{DS}=10V, V_{GS}=4.5V, V_{DS}=0.6A$		1.2	1.5	nC
Gate-Source Charge	$Q_{gs}$			0.2		
Gate-Drain Charge	$Q_{gd}$			0.3		
Turn-On Time	$T_{d(on)}$	$V_{DD}=10V, R_L=10\Omega, I_D=0.5A,$ $V_{GEN}=4.5V, R_G=6\Omega$		5	10	nS
	$t_r$			8	15	
Turn-Off Time	$T_{d(off)}$			10	18	
	$t_f$			1.2	2.8	

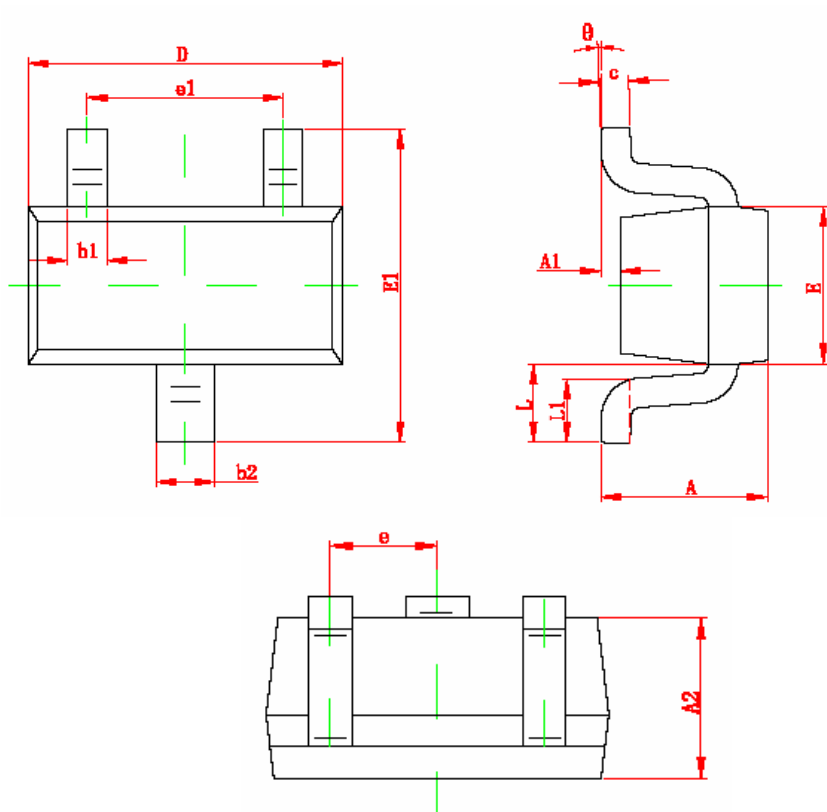
Dual N Channel Enhancement Mode MOSFET  
 0.65A

**TYPICAL CHARACTERISTICS**


Dual N Channel Enhancement Mode MOSFET  
0.65A

**TYPICAL CHARACTERISTICS**



**SOT523 (SC-89) PACKAGE OUTLINE**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.900	0.028	0.035
A1	0.000	0.100	0.000	0.004
A2	0.700	0.800	0.028	0.031
b1	0.150	0.250	0.006	0.010
b2	0.250	0.325	0.010	0.013
c	0.100	0.200	0.004	0.008
D	1.500	1.700	0.059	0.067
E	0.750	0.850	0.030	0.033
E1	1.450	1.750	0.057	0.069
e	0.500 TYP		0.020 TYP	
e1	0.900	1.100	0.035	0.043
L	0.550 REF		0.022 REF	
L1	0.280	0.440	0.011	0.017
theta	0°	4°	0°	4°